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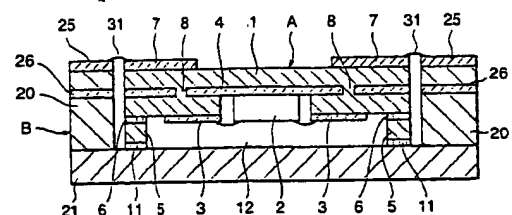
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(54) High-frequency module

(57) There is described a high-frequency module comprising a high-frequency device-mounting package and an external circuit board characterized in that said high-frequency device-mounting package (A) includes a dielectric substrate (1) having a first grounding layer (4) contained therein, said dielectric substrate (1) mounting a high-frequency device (2) on one surface thereof and having, formed on one surface thereof, first high-frequency signal transmission lines (3) connected to said high-frequency device (2), and having, formed on the other surface thereof, second high-frequency signal transmission lines (7) coupled to said first high-frequency signal transmission lines (3), said external circuit board (B) is constituted by a dielectric board (20) having third high-frequency signal transmission lines (25) and a second grounding layer (26), said third high-frequency signal transmission lines (25) being formed on one surface of said dielectric board (20), and said second grounding layer (26) being formed on the other surface of said dielectric board (20) or inside thereof; and said high-frequency device-mounting package (A) and said external circuit board (B) are arranged side by side, and the second high-frequency signal transmission lines (7) of the high-frequency device-mounting package (A) are electrically connected to the third high-frequency signal transmission lines (25) of the external circuit board (B) through linear electrically conducting members (31). The patterns of the second high-frequency

frequency signal transmission lines on the side of the high-frequency device-mounting package can be easily aligned with the patterns of the third high-frequency signal transmission lines on the side of the external circuit board, effectively reducing the transmission loss at the junction portions of the lines.

FIG. 1



EP 0 977 298 A2

Description

BACKGROUND OF THE INVENTION

[0001] The present invention relates to a high-frequency module in which a high-frequency device-mounting package mounting a high-frequency device operating on high-frequency signals of from a microwave band to a millimeter-wave band, is mounted on an external circuit board. More particularly, the invention relates to a high-frequency module in which a high-frequency device-mounting package (hereinafter often referred to simply as high-frequency package) is connected to an external circuit board without deteriorating characteristics of the high-frequency signals.

[0002] Conventional representative high-frequency modules equipped with a high-frequency package mounting a high-frequency device that operates on high-frequency signals of microwaves and millimeter waves, have structures as shown in Figs. 11a and 11b.

[0003] Referring, for example, to Fig. 11a, a high-frequency package 80 comprises a dielectric substrate 82 mounting a high-frequency device 81 which is air-tightly sealed in a cavity 85 formed by a frame 83 and a closure 84. On the surface of the dielectric substrate 82 are formed high-frequency signal transmission lines (hereinafter often referred to simply as high-frequency lines) 86 such as microstrip lines connected to the high-frequency device 81. The high-frequency lines 86 are drawn out of the cavity 85 through the frame 83 and extend to the back surface of the dielectric substrate 82 passing over the side surfaces of the dielectric substrate 82. That is, the high-frequency lines 86 on the back surface of the dielectric substrate 82 are connected to high-frequency lines 88 formed on an external circuit board 87 such as a mother board through an electrically conducting adhesive material 89 such as solder. High-frequency signals are input to the high-frequency device 81 through the high-frequency lines 86, or high-frequency signals are output to the high-frequency lines 86 from the high-frequency device 81. In the high-frequency module equipped with a plurality of high-frequency packages 80 as shown in Fig. 11a, furthermore, the high-frequency lines 86 on the back surface of the dielectric substrate 82 of each package 80 are connected to the high-frequency lines 88 of the external circuit board 87, so that the high-frequency packages 80 are electrically connected to each other.

[0004] A high-frequency module shown in Fig. 11b has the same structure as the high-frequency module of Fig. 11a except that the high-frequency lines 86 formed on the front and back surfaces of the dielectric substrate 82 of the high-frequency package 80 are connected together using the through-hole conductors 90 penetrating through the dielectric substrate 82. In the high-frequency module of Fig. 11a, the high-frequency lines 86 are drawn to the external side through the frame 83, involving such defects that the high-frequency signals

produce reflection loss and radiation loss at portions where the high-frequency lines 86 pass through the frame 83 and that characteristics of the high-frequency signals are deteriorated. Besides, since the high-frequency lines 86 are folded, high-frequency signals of the millimeter band produce a large reflection loss at the folded portions of the high-frequency lines 86, making it difficult to transmit or receive signals. In the high-frequency module of Fig. 11b, on the other hand, the high-frequency lines 86 formed on the front and back surfaces of the dielectric substrate 82 are connected together using the through-hole conductors 90, offering an advantage in that the above-mentioned reflection loss and radiation loss are decreased.

[0005] In the above-mentioned high-frequency modules of Figs. 11a and 11b, however, the high-frequency lines 86 of the high-frequency package are connected to the high-frequency lines 88 of the external circuit board through the electrically conducting adhesive material 89 such as solder, making it very difficult to accomplish the alignment between the patterns of the high-frequency lines 86 and the patterns of the high-frequency lines 88. Depending on the frequency of signals, therefore, there occurs reflection loss due to mismatching of the impedance at the connection portions using the electrically conducting adhesive material 89, whereby the transmission loss so increases that it often becomes difficult to transmit signals of high frequencies.

[0006] The object of the present invention, therefore, is to provide a high-frequency module which enables the patterns of high-frequency lines of a high-frequency package to be easily aligned with the patterns of high-frequency lines of an external circuit board, enabling the transmission loss of high-frequency signals to be effectively decreased at the junction portions of these lines.

[0007] According to the present invention, there is provided a high-frequency module comprising a high-frequency device-mounting package and an external circuit board; wherein

said high-frequency device-mounting package includes a dielectric substrate having a first grounding layer contained therein, said dielectric substrate mounting a high-frequency device on one surface thereof and having, formed on one surface thereof, first high-frequency signal transmission lines connected to said high-frequency device, and having, formed on the other surface thereof, second high-frequency signal transmission lines coupled to said first high-frequency signal transmission lines; said external circuit board is constituted by a dielectric board having third high-frequency signal transmission lines and a second grounding layer, said third high-frequency signal transmission lines being formed on one surface of said dielectric board, and said second grounding layer being formed on the other surface of said dielectric board or inside thereof; and

said high-frequency device-mounting package and said external circuit board are arranged side by side, and the second high-frequency signal transmission lines of the high-frequency device-mounting package are electrically connected to the third high-frequency signal transmission lines of the external circuit board through linear electrically conducting members.

[0008] The invention further provides a high-frequency device-mounting package equipped with a dielectric substrate having a grounding layer contained therein; wherein

said dielectric substrate mounts a high-frequency device on one surface thereof and has, formed on one surface thereof, first high-frequency signal transmission lines connected to said high-frequency device, and has, formed on the other surface thereof, second high-frequency signal transmission lines coupled to said first high-frequency signal transmission lines; and a connection portion is formed at the ends of said second high-frequency signal transmission lines for connecting linear electrically conducting members connected to an external circuit board.

[0009] In the high-frequency module of the present invention if briefly described, the high-frequency device-mounting package (high-frequency package) and the external circuit board are arranged side by side, and the second high-frequency signal transmission lines on the package and the third high-frequency signal transmission lines of the external circuit board are connected together through linear electrically conducting members such as wires, ribbons or electrically conducting tapes, making very important features. The module of the present invention having the above-mentioned structure offers an advantage in that when the high-frequency package is mounted on the external circuit board, the patterns of the second high-frequency signal transmission lines of the package can be easily aligned with the patterns of the third high-frequency signal transmission lines of the external circuit board, producing a small high-frequency signal transmission loss between the lines.

[0010] In the present invention, the first high-frequency signal transmission lines formed on one surface of the dielectric substrate in the high-frequency package and connected to the high-frequency device, can be directly connected to the second high-frequency signal transmission lines formed on the other surface of the dielectric substrate by using, for example, through-hole conductors. Desirably, however, they should be electromagnetically coupled together. When they are connected together by using through-hole conductors, the high-frequency signal transmission characteristics may often be deteriorated in the connected portions due to

signal transmission loss. When they are electromagnetically coupled together, however, no such inconvenience takes place. These lines can be easily electromagnetically coupled together by forming slots in the grounding layer in the dielectric substrate.

[0011] According to the present invention, furthermore, the grounding layer formed in the dielectric substrate in the high-frequency package is partly exposed. By utilizing the exposed surface of the grounding layer, the grounding layer of the package is connected to the grounding layer formed on the external circuit board or to the grounding layer of another package, in order to easily maintain constant at all times the gap between the grounding layer and the high-frequency signal transmission lines formed on the package or on the external circuit board thereby to decrease the transmission loss of high-frequency signals.

BRIEF DESCRIPTION OF THE DRAWINGS

[0012]

Fig. 1 is a side sectional view illustrating a structure of connection between a high-frequency device-mounting package and an external circuit board in a high-frequency module of the present invention; Fig. 2 is a plan view of the high-frequency module shown in Fig. 1;

Fig. 3 includes a plan view (a) and a side sectional view (b) for explaining the structure of an electromagnetic coupling portion formed in the high-frequency device-mounting package in the high-frequency module of Fig. 1;

Fig. 4 is a side sectional view illustrating a high-frequency module of the present invention on which a plurality of high-frequency device-mounting packages are mounted;

Fig. 5 is a plan view of the high-frequency module of Fig. 4;

Figs. 6 to 8 are side sectional views illustrating various connection structures among the high-frequency device-mounting packages in the high-frequency module of the present invention;

Fig. 9 is a perspective view illustrating a major portion in the connection structure of Fig. 8;

Fig. 10 is a side view illustrating another connection structure between the external circuit board and the high-frequency device-mounting package in the high-frequency module of the present invention; and

Figs. 11a and 11b are side sectional views illustrating conventional high-frequency packages.

DETAILED DESCRIPTION OF THE INVENTION

[0013] The invention will now be described in detail based upon the embodiments shown in the accompanying drawings.

[0014] Referring to Figs. 1 and 2 illustrating a structure of connection between a high-frequency device-mounting package in a high-frequency module and an external circuit board of the present invention, the module is constituted by the high-frequency device-mounting package (hereinafter referred to as high-frequency package) generally designated at A and an external circuit board (generally designated at B) arranged side by side relative to the package A.

[0015] The high-frequency package A includes a dielectric substrate 1 on which is mounted a high-frequency device 2 such as MMIC or MIC. To the high-frequency device 2 is electrically connected a first high-frequency signal transmission line (hereinafter often referred to simply as first high-frequency line) 3 that is formed on the dielectric substrate 1. High-frequency signals are input to, and output from, the high-frequency device 2 through the first high-frequency line 3. The connection between the high-frequency device 2 and the first high-frequency line 3 can be accomplished by using a linear electrically conducting member such as wire, ribbon or electrically conducting tape such as tape for TAB (tape automated bonding), or the two can be directly connected together relying upon the so-called flip-chip mounting.

[0016] A grounding layer (first grounding layer) 4 is formed in the dielectric substrate 1 nearly over the whole area of the dielectric substrate 1, and a microstrip line is constituted by the first high-frequency line 3 and the grounding layer 4.

[0017] An electromagnetic wave-shielding frame 5 is provided on the surface of the dielectric substrate 1 on the side

where the high-frequency device 2 is mounted so as to surround the high-frequency device 2. The frame 5 can be made of an electromagnetic wave-shielding material such as metal, electrically conducting ceramics, or ceramics-metal composite material. Besides, the frame 5 may be made of an insulating material which contains an electromagnetic wave-absorbing material such as carbon dispersed therein. Or, the electromagnetic wave-shielding property can be imparted by applying an electromagnetic wave-absorbing material onto the surface of the frame 5 formed of an insulating material. The frame 5 that is formed of a metal can be secured to the surface of the dielectric substrate 1 with a brazing material 6 as shown.

[0018] A pair of second high-frequency transmission lines (hereinafter often abbreviated as second high-frequency lines) 7 are formed on the surface of the dielectric substrate 1 of the opposite side (where the high-frequency device 2 is not mounted), and a microstrip line is constituted by the second high-frequency lines 7 and the grounding layer 4 in the dielectric substrate 1.

[0019] In the present invention, it is also allowable to form openings of a suitable size in the grounding layer 4, provide through-hole conductors through the openings, and connect the first high-frequency lines 3 and

the second high-frequency lines 7 together using the through-hole conductors. In order to lower the transmission loss of high-frequency signals, however, it is most desired to electromagnetically couple these lines 3 and 7 together. That is, as shown in Fig. 3, a slot 8 is formed in the grounding layer 4, and an end of the first high-frequency line 3 and an end of the second high-frequency line 7 are opposed to each other sandwiching the slot 8 therebetween; i.e., the two are electromagnetically coupled together through the slot 8.

[0020] It is desired that the slot 8 has a rectangular shape having a long side of a length L and a short side of a length M, but may have an elliptic shape having a long axis of a length L and a short axis of a length M. From the standpoint of enhancing the signal transmission efficiency, furthermore, it is desired that the length L of the long side (or long axis) of the slot 8 corresponds to one-half the wavelength λ of the transmission signals and the length M of the short side (or short axis) corresponds to 1/5 to 1/50 the wavelength λ of the transmission signals. As shown in Fig. 3(b), furthermore, the first high-frequency line 3 and the second high-frequency line 7 are so arranged that their ends are protruded by a length X beyond the center of the slot 8. It is desired that the length X of protrusion corresponds to about one-fourth the wavelength λ of the transmission signals.

[0021] As will be obvious from Fig. 2, furthermore, a pair of grounding portions 9, 9 are provided on both sides at each end of the pair of second high-frequency lines 7, and a connection portion is formed comprising a grounded coplanar line of the end of the line 7 and the grounding portions 9. That is, at this connection portion, the second high-frequency line 7 is connected to a high-frequency line formed on the external circuit board B. Though not diagramed, furthermore, the grounding portions 9 are electrically connected to the grounding layer 4 in the dielectric substrate 1 relying on the via-hole conductors or the castellations formed on the side surface of the dielectric substrate 1, and are maintained at the same potential as the grounding layer 4.

[0022] In the present invention, the external circuit board B is provided with a dielectric board 20 arranged side by side with respect to the dielectric substrate 1 of the high-frequency package A, the dielectric board 20 being connected to an electromagnetic wave-shielding plate 21 made of an electromagnetic wave-shielding material and, particularly, a metal like the above-mentioned frame 5. That is, as shown in Fig. 1, the frame 5 of the high-frequency package A is joined to the electromagnetic wave-shielding plate 21 using an electrically conducting adhesive material 11 such as solder or Au-Sn alloy, and a high-frequency device 2 is air-tightly sealed in a cavity 12 formed by the electromagnetic wave-shielding plate 21 and the frame 5, to effectively prevent the leakage of the electromagnetic waves from the high-frequency device 2 to the external side. It is also allowable to constitute the electromagnetic wave-shielding plate 21 by using an insulating material and

applying an electromagnetic wave-absorbing material onto the surface that forms the cavity 12.

[0023] A third high-frequency signal transmission line 25 is formed on the surface of the dielectric board 20, and a grounding layer (second grounding layer) 26 is formed in the dielectric board 20. That is, a microstrip line is constituted by the third high-frequency line 25 and the grounding layer 26. As will be obvious from Fig. 2, furthermore, a pair of grounding portions 27 and 27 are provided on both sides of an end of the third high-frequency line 25 at a position opposed to the connection portion formed for the second high-frequency line 7 of the high-frequency package A. A connection terminal 30 is formed comprising a grounded coplanar line of the line 25 and the grounding portions 27. The grounding portions 27 are electrically connected to the grounding layer 26 in the dielectric board 20 relying on the via-hole conductors or the castellation (not shown) formed on the side surface of the dielectric board 20, and are maintained at the same potential as the grounding layer 26.

[0024] According to the present invention, the connection terminal 30 formed at an end of the third high-frequency line 25 is connected to the connection portion formed for the second high-frequency line 7 of the high-frequency package A by using a linear electrically conducting member 31. That is, as shown in Fig. 2, the end of the third high-frequency line 25 and the end of the second high-frequency line 7 are connected together through the linear electrically conducting member 31, and the pair of grounding portions 27, 27 are connected to the pair of grounding portions 9, 9 through linear electrically conducting members 31. Wire, ribbon or tape for TAB such as an electrically conducting tape is used as the linear electrically conducting member 31.

[0025] In the high-frequency module of the present invention constituted as described above, the high-frequency package A is mounted on the external circuit board B, whereby the high-frequency device 2 is airtightly sealed preventing the leakage of the electromagnetic waves from the high-frequency device 2 to the external side. Besides, the connection between the third high-frequency line 25 of the external circuit board B and the second high-frequency line 7 of the high-frequency package A, is accomplished by using the linear electrically conducting member 31 instead of using an adhesive such as solder. Therefore, the lines 7 and 25 can be easily aligned, and the reflection loss of signals, due to the degradation of the alignment, at the connection portion between the two lines 7 and 25 can be effectively decreased compared with when the connection is accomplished by using solder or the like.

[0026] In the above-mentioned high-frequency module, the electric substrate 1 and the dielectric board 20 can be made of ceramics such as alumina, mullite, silicon nitride, silicon carbide or aluminum nitride, or glass ceramics, ceramics-metal composite material, glass-organic resin composite material, quartz, or various res-

ins. Moreover, the conductor members or conductor layers such as high-frequency lines 3, 7, 25, grounding layers 4, 26, and grounding portions 9, 27, can be formed of a low-resistance conductor such as Ag, Cu, Au, a high-melting metal such as W or Mo, or alloys thereof, which are widely known electrically conducting materials.

[0027] In the above-mentioned high-frequency module, a single high-frequency package A is mounted on the external circuit board B. However, a plurality of high-frequency packages A may be mounted on the external circuit board B. Figs. 4 and 5 are a side sectional view and a plan view of a high-frequency module on which a plurality of high-frequency packages A are mounted.

[0028] The two high-frequency packages A shown in Figs. 4 and 5 have quite the same structure as the high-frequency package shown in Fig. 1, and are connected to a common electromagnetic wave-shielding plate 21. The high-frequency device 2 in each package A is electromagnetically sealed by the plate 21 and the frame 5. The second high-frequency line 7 of one high-frequency package A is connected to the third high-frequency line 25 of the external circuit board B through the linear electrically conducting member 31, and the second high-frequency lines 7 of the two high-frequency packages A are connected to each other through the linear electrically conducting member 31.

[0029] That is, when a plurality of high-frequency packages A are to be mounted on the external circuit board B, the second high-frequency line 7 of at least one high-frequency package A is connected to the external circuit board B, and the second high-frequency lines 7 of the plurality of high-frequency packages A may be connected together through linear electrically conducting members 31. Owing to this structure, high-frequency signals can be input to the high-frequency packages A from the external circuit board B, high-frequency signals can be output to the external circuit board B from the high-frequency packages A, and high-frequency signals can be transmitted and received among the high-frequency packages A.

[0030] In the present invention mentioned above, the structures of the high-frequency package A and the external circuit board B are not limited to those shown in Figs. 1 to 5, but can be changed in a variety of ways. In Figs. 1 to 5, for example, the first to third high-frequency lines 3, 7 and 25 constitute a microstrip line. These lines, however, may constitute a strip line or a grounded coplanar line. On the high-frequency package A, furthermore, there may be formed lines having other objects, such as a low-frequency wiring layer for feeding power to the high-frequency device 2, in addition to the lines for transmitting signals. The low-frequency wiring layer may be drawn on the surface of the dielectric substrate 1 where the second high-frequency lines 7 are formed, and may be connected to a power-source circuit formed on the external circuit B by using a linear electrically conducting member like the second high-fre-

quency line 7. The external circuit board B may also have a function of a mother board constituted by a printed board, or of a housing or a heat sink.

[0031] In the above-mentioned high-frequency module, the frame 5 surrounding the high-frequency device 2 of the high-frequency package A may be formed integrally with the electromagnetic wave-shielding plate 31. It is further possible to form an exposed surface on the grounding layer 4 provided in the dielectric substrate 1 of the high-frequency package A to easily connect together the grounding layers 4 of the plurality of packages A by utilizing the exposed surfaces, or to connect the grounding layer 4 of the package A to the grounding layer 26 of the external circuit board B by utilizing the exposed surfaces. In the high-frequency module in which the grounding layers are connected together by forming exposed surfaces on the grounding layers 4, the connection operation is facilitated. Besides, even when the thickness of the dielectric substrate 1 is increased to improve the strength, by forming the grounding layers in the same plan, the gap can be maintained constant at all times between the grounding layer and the high-frequency line formed on the high-frequency package A or on the external circuit board B. For example, the gap can be maintained constant on the connecting portion of the packages A, or of the package A and the circuit board B, too. Therefore, the transmission loss of signals can be decreased at the connecting portion. Figs. 6 to 10 illustrate the structures of connection of the high-frequency packages A in which the exposed surfaces are formed on the grounding layer 4.

[0032] The two high-frequency packages A1 and A2 shown in Fig. 6 have substantially the same structure, and are mounted on the external circuit board (not shown) by firmly adhering the electromagnetic wave-shielding frame 5 on the electromagnetic wave-shielding plate 21. It is also allowable to form the electromagnetic wave-shielding plate 21 and the frame 5 integrally together, so that the dielectric substrate 1 is joined to the thus integrally formed article.

[0033] Like the above-mentioned high-frequency package A, the packages A1 and A2 have the first high-frequency line 3 formed on the surface of the dielectric substrate 1 on the side on where the high-frequency device 2 is mounted, and have the second high-frequency line 7 formed on the surface of the dielectric substrate 1 of the opposite side. The dielectric substrate 1 has a structure in which the dielectric layer 1a and the dielectric layer 1b are laminated one upon the other, and has the grounding layer 4 sandwiched between the dielectric layer 1a and the dielectric layer 1b. As will be obvious from Fig. 6, furthermore, an opening of a suitable size is formed in the grounding layer 4, and the first high-frequency line 3 and the second high-frequency line 7 are electrically connected together through the via-hole conductor 40 extending passing through the opening. Moreover, the high-frequency lines 7 of the packages are electrically connected together through

the linear electrically conducting member 31.

[0034] In an embodiment of Fig. 6, the most significant feature resides in that exposed surfaces 45a and 45b are formed on the grounding layer 4. That is, in each package, the dielectric layers 1a and 1b are laminated being deviated from each other. In a portion on the right side of the grounding layer 4, the lower side is exposed to form the exposed surface 45a and in a portion on the left side, the upper side is exposed to form the exposed surface 45b. The package A1 and the package A2 are joined together in a manner that the exposed surfaces 45a and 45b of the grounding layers 4 are overlapped one upon the other. Therefore, the grounding layers 4 of the high-frequency packages mounted on the high-frequency module are nearly in flush with each other. As a result, the distribution of the electromagnetic field by the high-frequency signals is not disturbed by a dispersion in the position of the grounding layers 4, and favorable high-frequency transmission characteristics are maintained.

[0035] In an embodiment of Fig. 7, a metallic electromagnetic wave-shielding plate 21 is formed integrally with the electromagnetic wave-shielding frame 5, and has a protuberance 48 that corresponds to the frame 5. The high-frequency packages A3 and A4 shown in Fig. 7 have substantially the same structure as the high-frequency package A shown in Fig. 1. In these packages A3 and A4, however, an exposed surface 50 is formed on the grounding layer 4 in the dielectric substrate 1. That is, the dielectric substrate 1 is constituted by a laminate of the dielectric layers 1a and 1b, and the grounding layer 4 is formed between these layers, the dielectric layer 1b of the lower side being smaller than the dielectric layer 1a of the upper side. Therefore, the grounding layer 4 has the exposed surface 50 that is exposed on the lower side.

[0036] In the high-frequency packages A3 and A4 shown in Fig. 7, therefore, the second high-frequency lines 7 are electrically connected together through the linear electrically conducting member 31, and the exposed surface 50 is intimately adhered to the upper end of the protuberance 48 of the metallic plate 21, so that the grounding layers 4 are electrically connected to each other, the grounding layers 4 of the packages being positioned in flush with each other like in the embodiment of Fig. 6, making it possible to obtain favorable high-frequency transmission characteristics.

[0037] According to the connection structure using high-frequency packages shown in Figs. 6 and 7, the grounding layers 4 of the packages are positioned in flush irrespective of the thickness of the dielectric substrate 1 making it possible to maintain favorable high-frequency transmission characteristics. In particular, the lower dielectric layer 1b of the dielectric substrate 1 is thickly formed to enhance the strength of the dielectric substrate 1 without adversely affecting the high-frequency transmission characteristics.

[0038] In Figs. 6 and 7, the high-frequency packages

were connected together. It will, however, be understood that the exposed surface same as the one shown in these drawings may be formed on the grounding layer 26 provided in the dielectric board 20 of the external circuit board B shown in Fig. 1, so that the grounding layer 26 is formed in flush with the grounding layer 4, in order to maintain more favorable high-frequency transmission characteristics.

[0039] According to the present invention, furthermore, the exposed surfaces formed on the grounding layers 4 can be connected together by using a linear electrically conducting member. Figs. 8 to 10 illustrate examples for connecting the exposed surfaces of the grounding layers using the electrically conducting member.

[0040] Referring to Fig. 8, the high-frequency packages A5 and A6 have the same structure as the high-frequency packages A1 and A2 shown in Fig. 6 except the state of the exposed surfaces formed on the grounding layers 4. That is, the grounding layer 4 is arranged between the dielectric layers 1a and 1b constituting the dielectric substrate 1. Besides, the first high-frequency line 3 is connected to the high-frequency device 2 mounted on one surface of the dielectric substrate 1, and the second high-frequency line 7 is formed on the other surface of the dielectric substrate 1. An opening of a suitable size is formed in the grounding layer 4, and the first high-frequency line 3 and the second high-frequency line 7 are electrically connected together using the through-hole conductor 40 extending passing through the opening. The packages A1 and A2 are joined to the electromagnetic wave-shielding plate 21 by the electromagnetic wave-shielding frame 5.

[0041] Referring to Fig. 9 illustrating the structure of the connection portion at an end of the second high-frequency line 7 in the packages A5 and A6 in Fig. 8, cut-away portions 55 are formed in the dielectric layer 1a on both sides at the end of the second high-frequency line 7. As a result, exposed surfaces 56 are formed in the grounding layer 4.

[0042] That is, as will be obvious from Fig. 8, the second high-frequency lines 7 are connected together through the linear electrically conducting member 31 in the packages A5 and A6, and the exposed surfaces 56 of the grounding layers 4 are connected together through the linear electrically conducting member 31.

[0043] The high-frequency module of Fig. 10 uses a metal case 60 that works as an electromagnetic wave-shielding plate. A high-frequency package A7 and an external circuit board B are mounted in the metal case 60.

[0044] The metal case 60 includes a bottom wall 60a and a side wall 60b, and an electromagnetic wave-shielding frame 5 provided on the surface of the dielectric substrate 1 of the high-frequency package A7 is firmly adhered onto the bottom wall 60a. A stepped surface 65 is formed in the inner surface of the side wall 60b, and the external circuit board B is mounted on the

stepped surface 65. That is, the dielectric board 20 of the external circuit board B is mounted on the stepped surface 65 and, hence, the metal case 60 also works as a grounding layer for the external circuit board B.

[0045] The high-frequency package A7 substantially has a structure similar to that of the high-frequency package A of Fig. 1, and the dielectric substrate 1 is formed by laminating the dielectric layers 1a and 1b, and the grounding layer 4 having a slot 8 is sandwiched therebetween. Furthermore, the first high-frequency line 3 connected to the high-frequency device 2 mounted on one surface of the dielectric substrate 1 (lower surface in Fig. 10) and the second high-frequency line 7 formed on the other surface of the dielectric substrate 1, are electromagnetically coupled together through the slot 8.

[0046] In the thus constituted module, cut-away portions 55 are formed in the dielectric layer 1a on both sides of an end of the second high-frequency line 7 in quite the same manner as in Fig. 9, and the exposed surface is formed on the grounding layer 4. On the other hand, the dielectric board 20 of the external circuit board B is arranged side by side relative to the dielectric layer 1a of the upper side of the dielectric substrate 1 (or, in other words, the stepped surface 65 of the metal case 60 and the grounding layer 4 are positioned nearly in flush with each other). The third high-frequency line 25 formed on the upper surface of the dielectric board 20 is arranged to be opposed to the end of the second high-frequency line 7 of the high-frequency package A7, the cut-away portions 58 are formed in the dielectric board 20 on both sides of the end, and the stepped surface 65 formed on the metal case 60 is exposed at these portions. That is, the cut-away portions 55 formed in the dielectric layer 1a of the high-frequency package A7 are opposed to the cut-away portions 58 formed in the dielectric board 20 of the external circuit board B. As shown in Fig. 10, therefore, the second high-frequency line 7 of the high-frequency package A7 and the third high-frequency line 25 of the external circuit board B are electrically connected together through the linear electrically conducting member 31, and the exposed surfaces of the grounding layers 4 formed by the cut-away portions 55, 58, and the exposed surfaces on the stepped surface 65 are electrically connected together through the linear electrically conducting members 31.

[0047] In the high-frequency modules having structures shown in Figs. 8 and 10, too, the grounding layers in the high-frequency packages and the grounding layer provided in the external circuit board are positioned substantially in flush with each other and are electrically connected together, effectively preventing the disturbance in the distribution of the electromagnetic field caused by high-frequency signals, and maintaining favorable high-frequency transmission characteristics.

Claims

1. A high-frequency module comprising a high-frequency device-mounting package and an external circuit board characterized in that

said high-frequency device-mounting package (A) includes a dielectric substrate (1) having a first grounding layer (4) contained therein, said dielectric substrate (1) mounting a high-frequency device (2) on one surface thereof and having, formed on one surface thereof, first high-frequency signal transmission lines (3) connected to said high-frequency device (2), and having, formed on the other surface thereof, second high-frequency signal transmission lines (7) coupled to said first high-frequency signal transmission lines (3), said external circuit board (B) is constituted by a dielectric board (20) having third high-frequency signal transmission lines (25) and a second grounding layer (26), said third high-frequency signal transmission lines (25) being formed on one surface of said dielectric board (20), and said second grounding layer (26) being formed on the other surface of said dielectric board (20) or inside thereof; and said high-frequency device-mounting package (A) and said external circuit board (B) are arranged side by side, and the second high-frequency signal transmission lines (7) of the high-frequency device-mounting package (A) are electrically connected to the third high-frequency signal transmission lines (25) of the external circuit board (B) through linear electrically conducting members (31).

2. A high-frequency module according to claim 1, wherein a slot is formed in the first grounding layer of said high-frequency device-mounting package, and the first high-frequency signal transmission line and the second high-frequency signal transmission line are electromagnetically coupled together through said slot.
3. A high-frequency module according to claim 1 or 2, wherein an opening is formed in the first grounding layer of said high-frequency device-mounting package, and the first high-frequency signal transmission line and the second high-frequency signal transmission line are coupled together using a through-hole conductor that penetrates the dielectric substrate passing through said opening.
4. A high-frequency module according to any of claims 1 to 3, wherein said linear electrically conducting member is selected from the group consisting of wire, ribbon and electrically conducting tape.

5. A high-frequency module according to any of claims 1 to 4, wherein an electromagnetic wave-shielding member is joined to the surface of said dielectric substrate on the side where the high-frequency device is mounted, and said high-frequency device is air-tightly sealed by the dielectric substrate and the electromagnetic wave-shielding member.

6. A high-frequency module according to any of claims 1 to 5, wherein a pair of grounding portions electrically connected to the first grounding layer or the second grounding layer are formed on both sides of an end of the second high-frequency signal transmission line of said high-frequency device-mounting package and on both sides of an end of the third high-frequency signal transmission line of the external circuit board, and the second high-frequency signal transmission line and the third high-frequency signal transmission line are electrically connected together through said linear electrically conducting member, and the grounding portions on both sides of the second high-frequency line and the grounding portions on both sides of the third high-frequency line are electrically connected together through said linear electrically conducting members.

7. A high-frequency module according to any of claims 1 to 6, wherein exposed surfaces are formed on the first grounding layer of said high-frequency device-mounting package and on the second grounding layer of said external circuit board, and said exposed surfaces are electrically connected together through an electrically conducting member attached to said electromagnetic wave-shielding member.

8. A high-frequency module according to any of claims 1 to 6, wherein exposed surfaces are formed on the first grounding layer of said high-frequency device-mounting package and on the second grounding layer of said external circuit board, and said exposed surfaces are joined together in a manner of being overlapped one upon the other thereby to electrically connect the first grounding layer and the second grounding layer together.

9. A high-frequency module according to any of claims 1 to 6, wherein exposed surfaces are formed on the first grounding layer of said high-frequency device-mounting package and on the second grounding layer of said external circuit board, and said exposed surfaces are electrically connected together through a linear connection member.

10. A high-frequency module according to any of claims 1 to 9, wherein a plurality of external circuit

boards are joined to a common electromagnetic wave-shielding member.

11. A high-frequency module according to claim 10, wherein said electromagnetic wave-shielding member is a metallic case which contains said high-frequency device-mounting package and said external circuit board.
12. A high-frequency module according to any of claims 1 to 11, wherein said high-frequency device-mounting packages are mounted in a plural number, the second high-frequency signal transmission lines of the packages are electrically connected together through a linear electrically conducting member, and the second high-frequency signal transmission line of at least one package is connected to the third high-frequency signal transmission line of said external circuit board.
13. A high-frequency module according to claim 12, wherein the surface of the dielectric substrate, of each of the packages, on the side on where the high-frequency device is mounted is joined to a common electromagnetic wave-shielding member, and the high-frequency device mounted on each package is air-tightly sealed by the common electromagnetic wave-shielding member and said dielectric substrate.
14. A high-frequency module according to claim 12 or 13, wherein a pair of grounding portions are formed on both sides of an end of the second high-frequency signal transmission line in each of the packages to form a grounded coplanar line, and the grounding portions of the grounded coplanar lines are connected together through a linear electrically conducting member, and the ends of the second high-frequency signal transmission lines are connected together through a linear electrically conducting member.
15. A high-frequency module according to any of claims 12 to 14, wherein an exposed surface is formed on the first grounding layer of each package, and the exposed surfaces are electrically connected together through an electrically conducting member attached to said electromagnetic wave-shielding member.
16. A high-frequency module according to any of claims 12 to 14, wherein an exposed surface is formed on the first grounding layer of each package, and the exposed surfaces are joined together in a manner of being overlapped one upon the other, so that the first grounding layers of the packages are electrically connected together.

17. A high-frequency module according to any of claims 12 to 14, wherein an exposed surface is formed on the first grounding layer of each package, and the exposed surfaces are electrically connected together through a linear electrically conducting member.

18. A high-frequency module according to any of claims 13 to 17, wherein said electromagnetic wave-shielding member is a metal case containing a plurality of said high-frequency device-mounting packages and said external circuit board.

19. A high-frequency device-mounting package equipped with a dielectric substrate having a grounding layer contained therein, characterized in that

said dielectric substrate mounts a high-frequency device on one surface thereof and has, formed on one surface thereof, first high-frequency signal transmission lines connected to said high-frequency device, and has, formed on the other surface thereof, second high-frequency signal transmission lines coupled to said first high-frequency signal transmission lines; and

a connection portion is formed at the ends of said second high-frequency signal transmission lines for connecting linear electrically conducting members connected to an external circuit board.

20. A high-frequency device-mounting package according to claim 19, wherein a pair of grounding portions electrically connected to the grounding layer in said dielectric substrate are formed on both sides of an end of said second high-frequency signal transmission line.

21. A high-frequency device-mounting package according to any of claim 19 or 20, wherein the grounding layer in said dielectric substrate is partly exposed at the connection portion formed at an end of said second high-frequency signal transmission line.

22. A high-frequency device-mounting package according to claim 21, wherein the dielectric substrate is cut away on both sides of an end of said second high-frequency signal transmission line so that the grounding layer is exposed.

23. A high-frequency device-mounting package according to any of claims 19 to 23, wherein said grounding layer is exposed on the surface of the dielectric substrate on the side on where the high-frequency device is mounted, at a portion corre-

sponding to an end of said second high-frequency signal transmission line.

24. A high-frequency device-mounting package according to any of claims 19 to 23, wherein a slot is formed in the grounding layer, and the first high-frequency signal transmission line and the second high-frequency signal transmission line are electromagnetically coupled together through said slot.

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25. A high-frequency device-mounting package according to any of claims 19 to 23, wherein an opening is formed in the grounding layer, and the first high-frequency signal transmission line and the second high-frequency signal transmission line are coupled together via a through-hole conductor that penetrates the dielectric substrate passing through said opening.

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FIG. 3

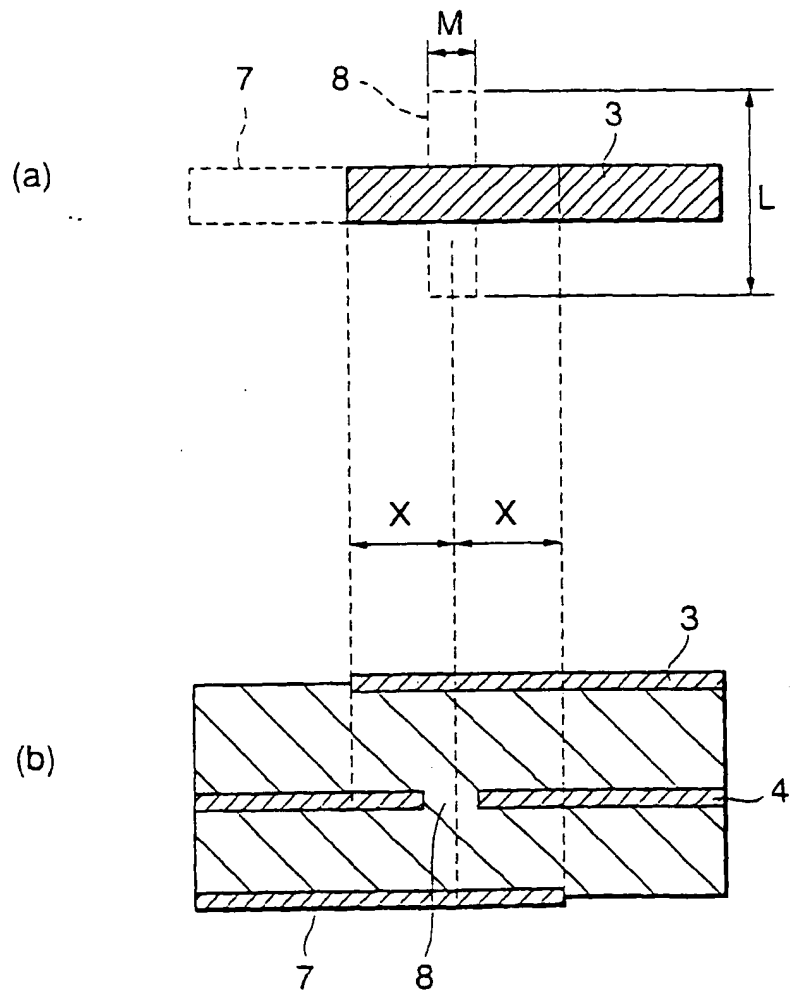


FIG. 4

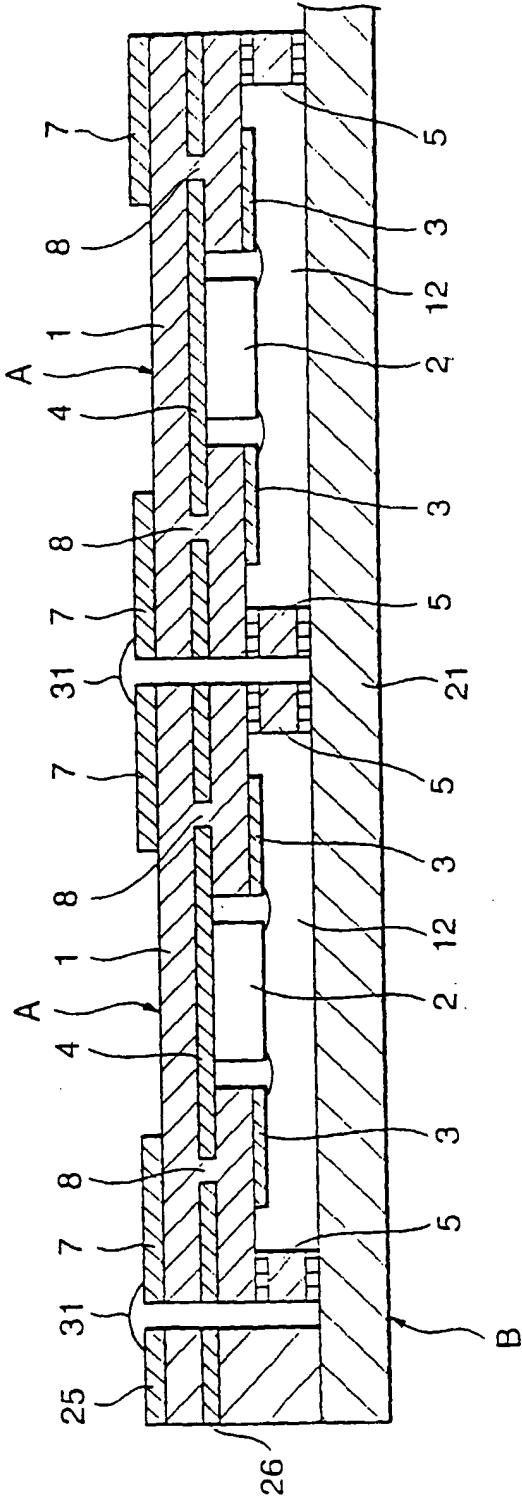


FIG. 5

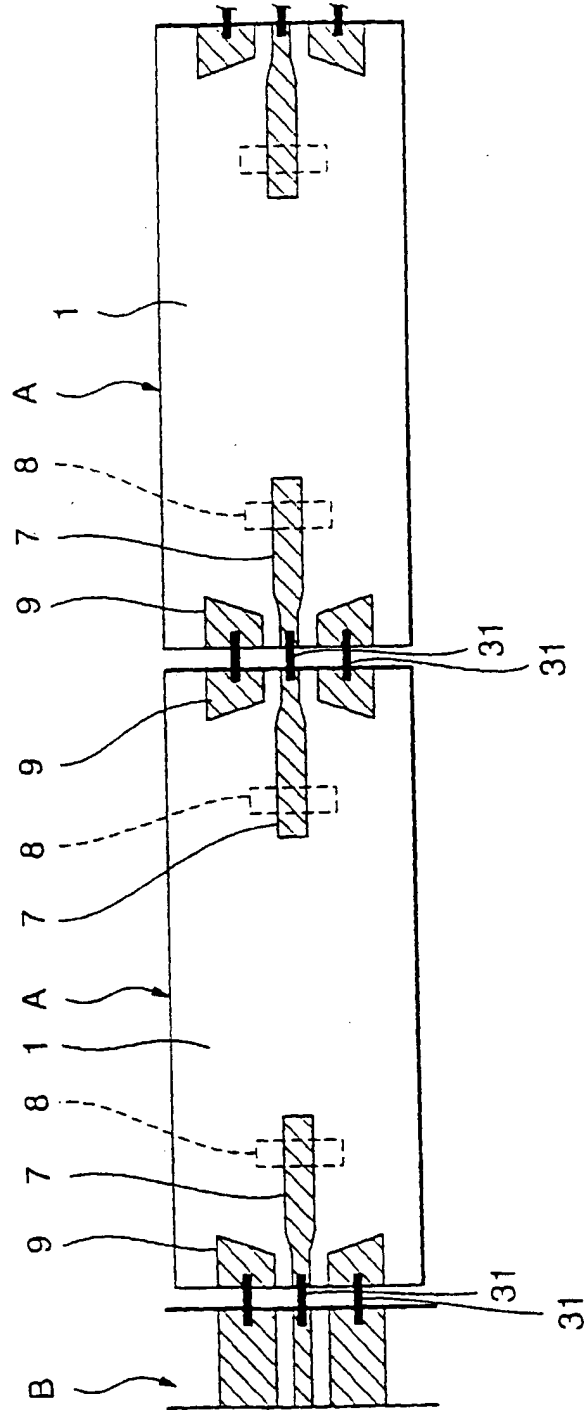


FIG. 6

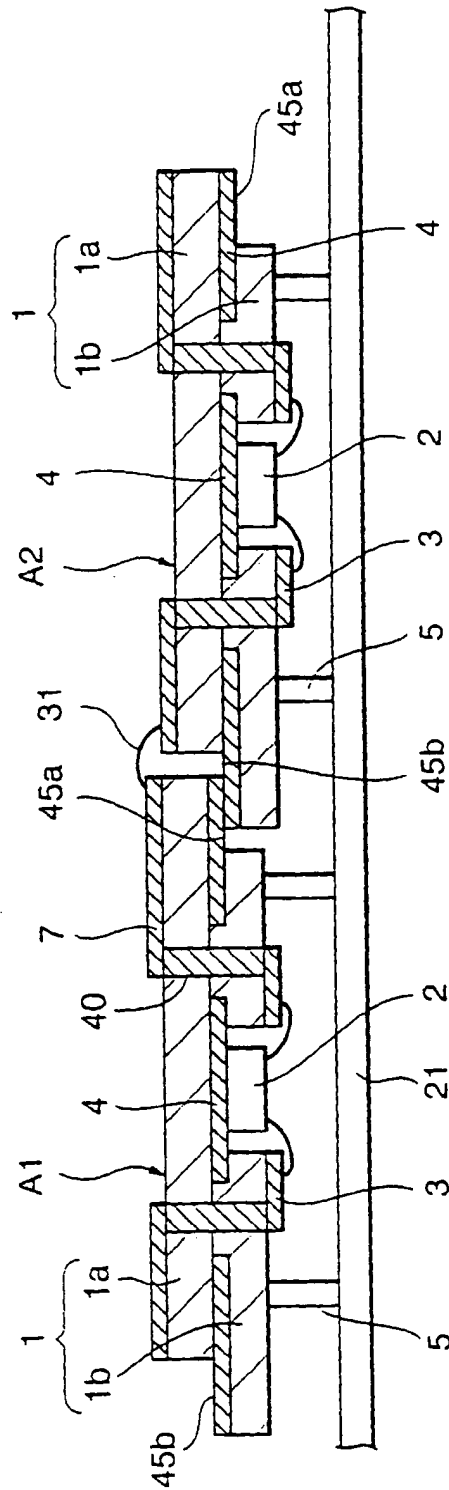


FIG. 7

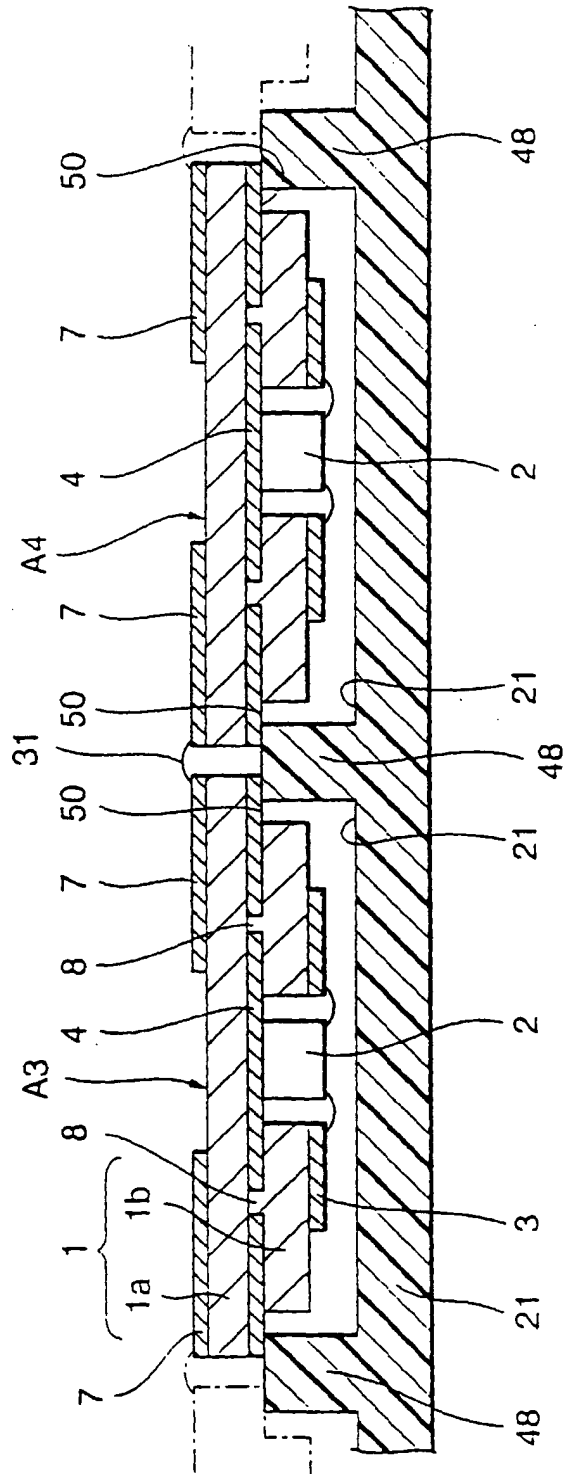


FIG. 8

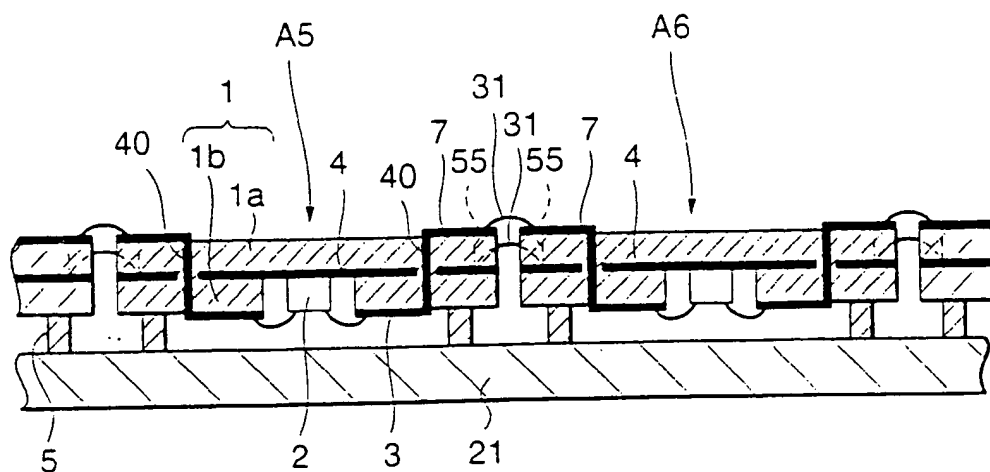


FIG. 9

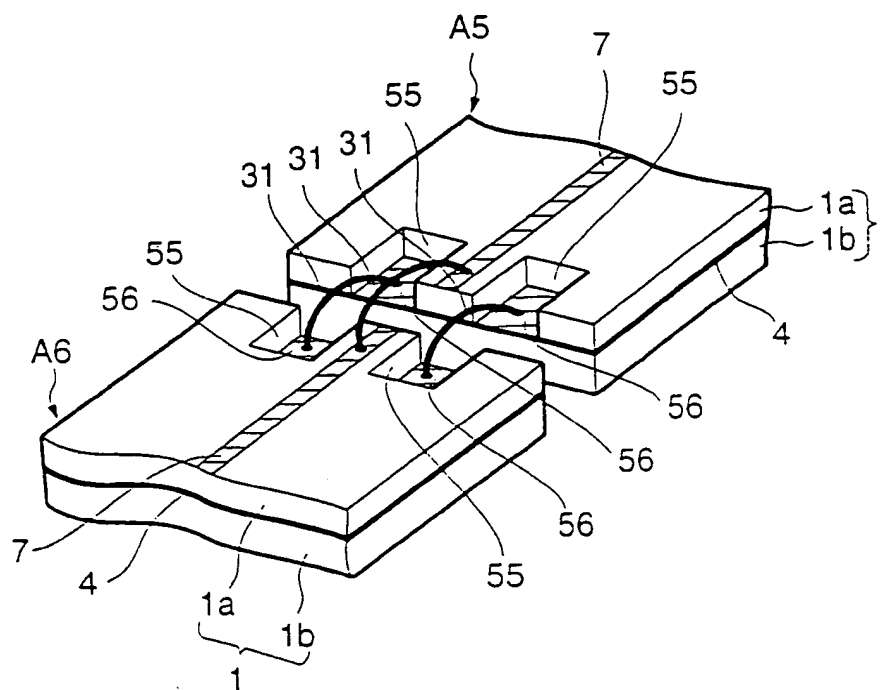


FIG. 10

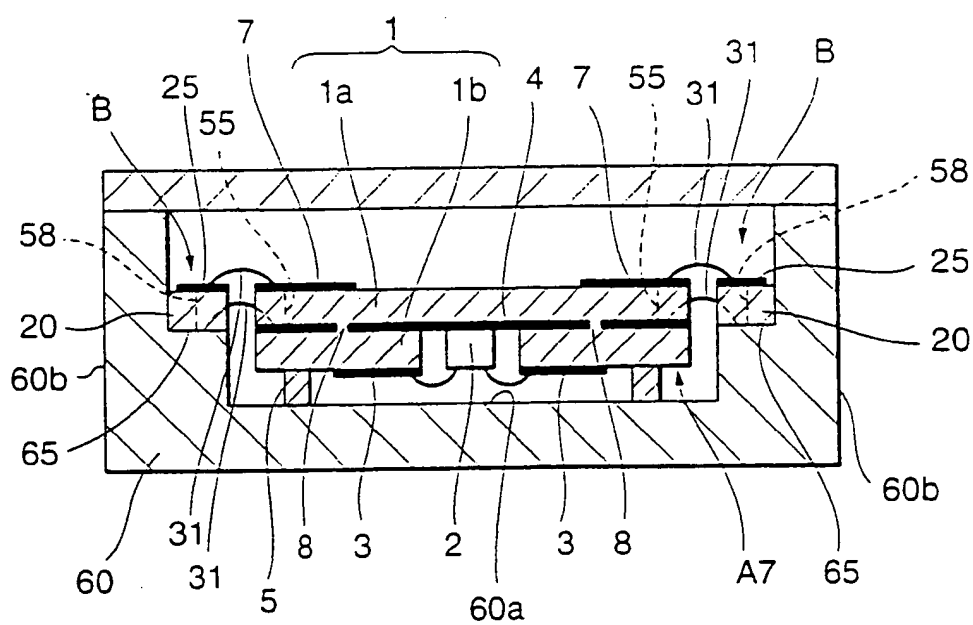


FIG. 11a

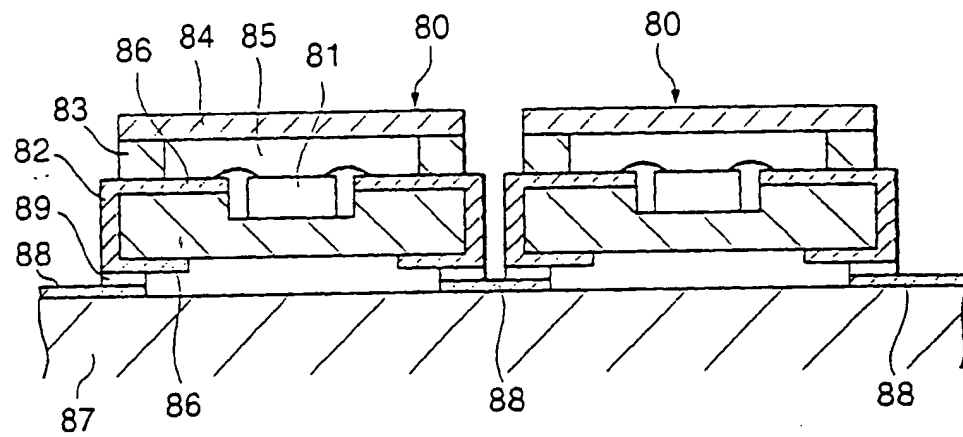
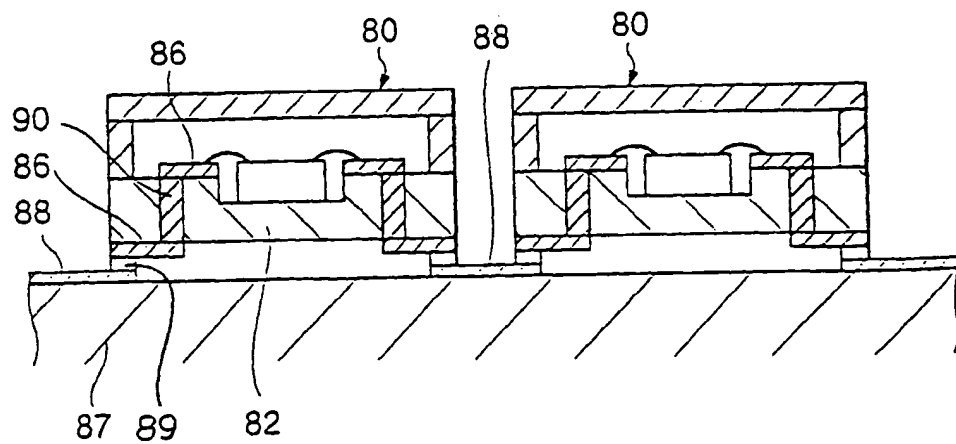
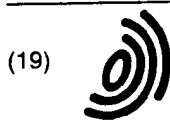


FIG. 11b





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(54) High-frequency module

(57) There is described a high-frequency module comprising a high-frequency device-mounting package and an external circuit board characterized in that said high-frequency device-mounting package (A) includes a dielectric substrate (1) having a first grounding layer (4) contained therein, said dielectric substrate (1) mounting a high-frequency device (2) on one surface thereof and having, formed on one surface thereof, first high-frequency signal transmission lines (3) connected to said high-frequency device (2), and having, formed on the other surface thereof, second high-frequency signal transmission lines (7) coupled to said first high-frequency signal transmission lines (3), said external circuit board (B) is constituted by a dielectric board (20) having third high-frequency signal transmission lines (25) and a second grounding layer (26), said third high-frequency signal transmission lines (25) being formed on one surface of said dielectric board (20), and said

second grounding layer (26) being formed on the other surface of said dielectric board (20) or inside thereof; and said high-frequency device-mounting package (A) and said external circuit board (B) are arranged side by side, and the second high-frequency signal transmission lines (7) of the high-frequency device-mounting package (A) are electrically connected to the third high-frequency signal transmission lines (25) of the external circuit board (B) through linear electrically conducting members (31). The patterns of the second high-frequency signal transmission lines on the side of the high-frequency device-mounting package can be easily aligned with the patterns of the third high-frequency signal transmission lines on the side of the external circuit board, effectively reducing the transmission loss at the junction portions of the lines.

EP 0 977 298 A3



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EUROPEAN SEARCH REPORT

Application Number
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A	--- US 4 827 327 A (MIYAUCHI ET AL.) 2 May 1989 (1989-05-02) * column 3, line 37 - column 4, line 56; figure 1 *	1,3,19	
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			H01P H05K H01L
The present search report has been drawn up for all claims			
Place of search		Date of completion of the search	Examiner
THE HAGUE		30 August 2001	Den Otter, A
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